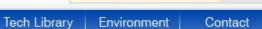
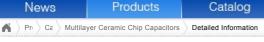
Catalog

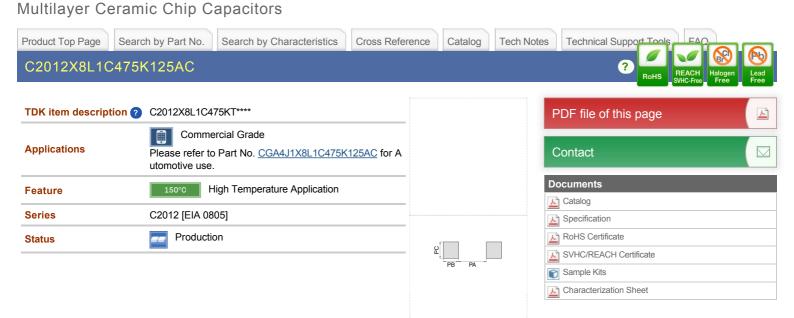
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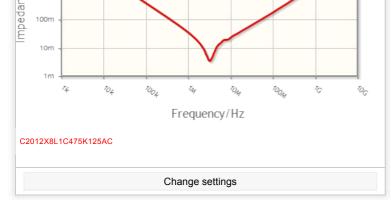
Application Guides Technical Support

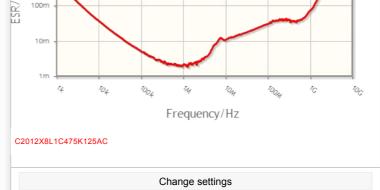
	and show exemplary products.
Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Electrical Characteristics	
Capacitance	4.7µF ±10%
Rated Voltage	16VDC
Temperature Characteristic ?	X8L(+15,-40%)
Dissipation Factor (Max.)	5%

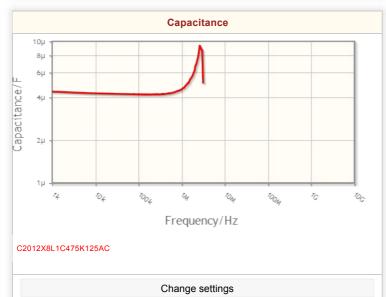
Insulation Resistance (Min.)	21ΜΩ
Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

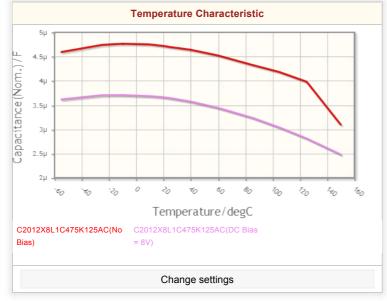


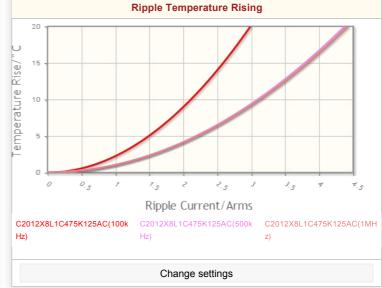












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» Selection Guide » Search by Part No. » Search by Characteristics » Distributor Inventory Check

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» Inductors (Coils)

» EMC Components

» RF Components and Modules

» Voltage / Current / Temperature Protection Devices

» Sensors and Sensor Systems

» Ceramic Switching / Heating, Piezo Components,

Buzzers and Microphones

» Transformers

» Ferrites and Accessories

» Noise Suppressing / Magnetic Sheet

- » Anechoic Chambers and Radio Wave Absorbers
- » Power Supplies
- » Magnets
- » Flash Storages
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